Lighting Color

• Red

# LNJ212R8ARA

Surface Mounting Chip LED

TSS Type

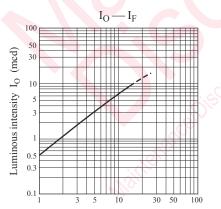
#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

項目	記号 定格		単位	
Power dissipation	P <sub>D</sub>	50	mW	
Forward current	$I_{\rm F}$	20	mA	
Pulse forward current *	I <sub>FP</sub>	60	mA	
Reverse voltage	V <sub>R</sub>	3	V	
Operating ambient temperature	T <sub>opr</sub>	-30 to +85	°C	
Storage temperature	T <sub>stg</sub>	-40 to +100	°C	

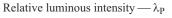
Note) \*: The condition of IFP is duty 10%, Pulse width 1 msec.

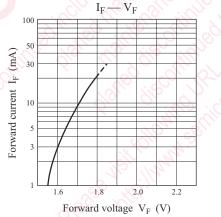
### Electro-Optical Characteristics $T_a = 25^{\circ}C$

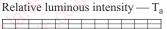
項目	記号	条件	最小	標準	最大	単位
Luminous intensity	I <sub>O</sub>	$I_F = 10 \text{ mA}$	2.2	6.7		mcd
Reverse current	I <sub>R</sub>	$V_R = 3 V$			100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 10 \text{ mA}$		1.72	2.5	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 10 \text{ mA}$	00	655	CO.	nm
Spectral half band width	Δλ	$I_{\rm F} = 10  {\rm mA}$	5	. 20	101	nm

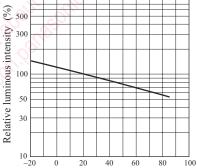




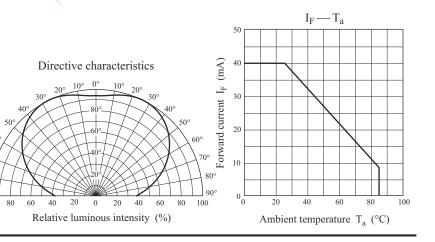








Ambient temperature  $T_a$  (°C)



1 0 0 0

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600

Peak emission wavelength  $\lambda_P$  (nm)

650

Relative luminous intensity (%)

100

80

60

40

20

0 550

SHD00428BEK

60

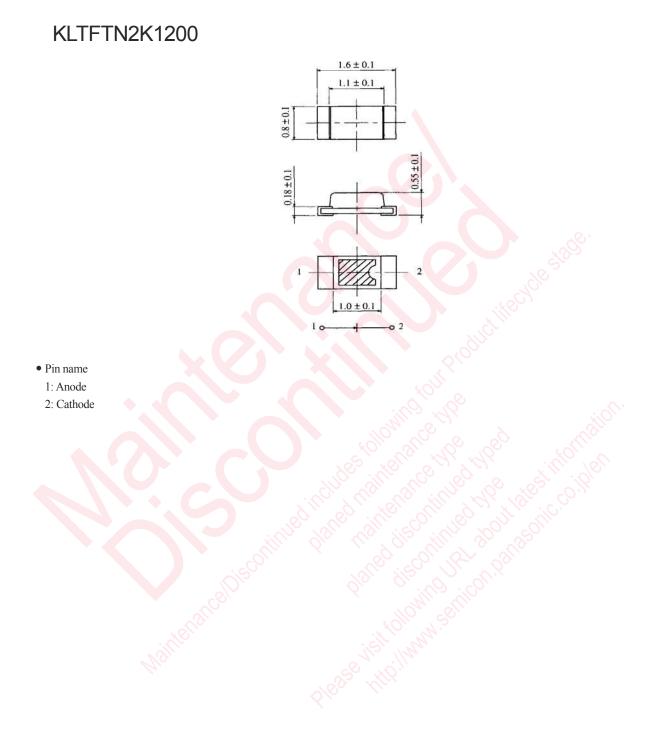
80

90°

700 100

#### LNJ212R8ARA

Package (Unit: mm)



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